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### Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	68
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LBGA
Supplier Device Package	100-FBGA (11x11)
Purchase URL	<a href="https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=epm7064bfc100-5">https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=epm7064bfc100-5</a>

**Table 3. MAX 7000B Maximum User I/O Pins** *Note (1)*

Device	44-Pin PLCC	44-Pin TQFP	48-Pin TQFP (2)	49-Pin 0.8-mm Ultra FineLine BGA (3)	100- Pin TQFP	100-Pin FineLine BGA (4)	144- Pin TQFP	169-Pin 0.8-mm Ultra FineLine BGA (3)	208- Pin PQFP	256- Pin BGA	256-Pin FineLine BGA (4)
EPM7032B	36	36	36	36							
EPM7064B	36	36	40	41	68	68					
EPM7128B				41	84	84	100	100			100
EPM7256B					84		120	141	164		164
EPM7512B							120	141	176	212	212

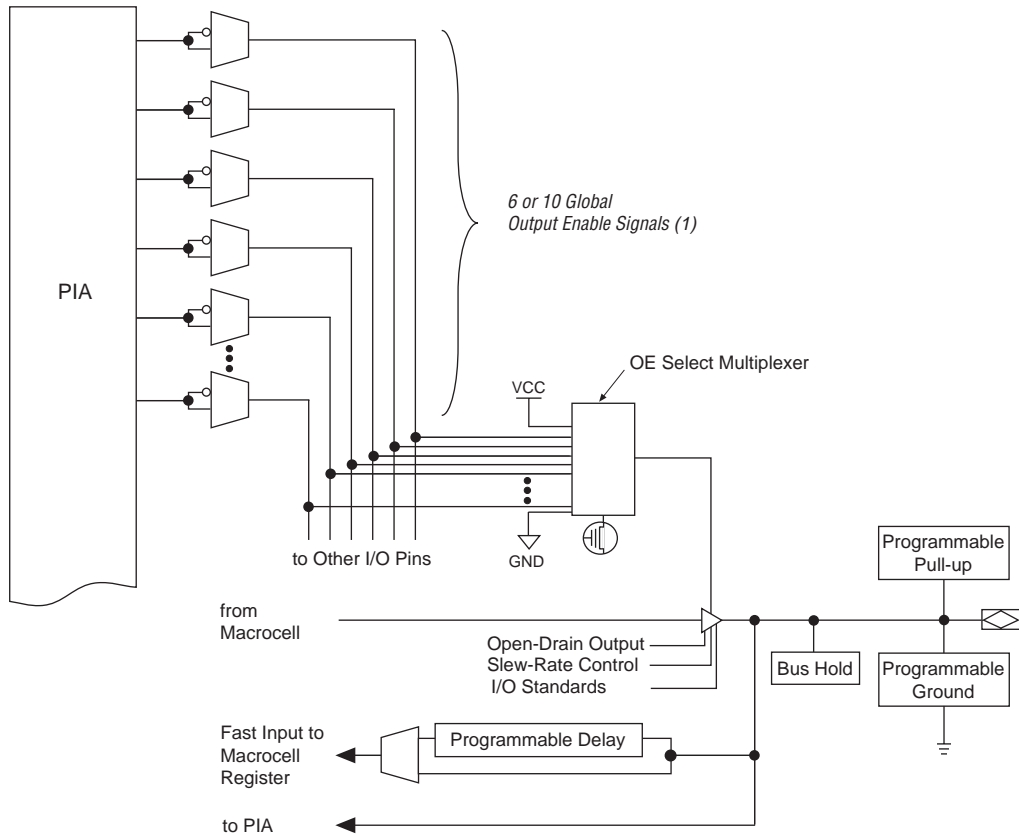
**Notes:**

- (1) When the IEEE Std. 1149.1 (JTAG) interface is used for in-system programming or boundary-scan testing, four I/O pins become JTAG pins.
- (2) Contact Altera for up-to-date information on available device package options.
- (3) All 0.8-mm Ultra FineLine BGA packages are footprint-compatible via the SameFrame™ pin-out feature. Therefore, designers can design a board to support a variety of devices, providing a flexible migration path across densities and pin counts. Device migration is fully supported by Altera development tools. See [“SameFrame Pin-Outs” on page 14](#) for more details.
- (4) All FineLine BGA packages are footprint-compatible via the SameFrame pin-out feature. Therefore, designers can design a board to support a variety of devices, providing a flexible migration path across densities and pin counts. Device migration is fully supported by Altera development tools. See [“SameFrame Pin-Outs” on page 14](#) for more details.

MAX 7000B devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000B architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000B devices contain 32 to 512 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

Figure 6. I/O Control Block of MAX 7000B Devices

**Note:**

- (1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enable signals. EPM7512B devices have ten output enable signals.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to  $V_{CC}$ , the output is enabled.

The MAX 7000B architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

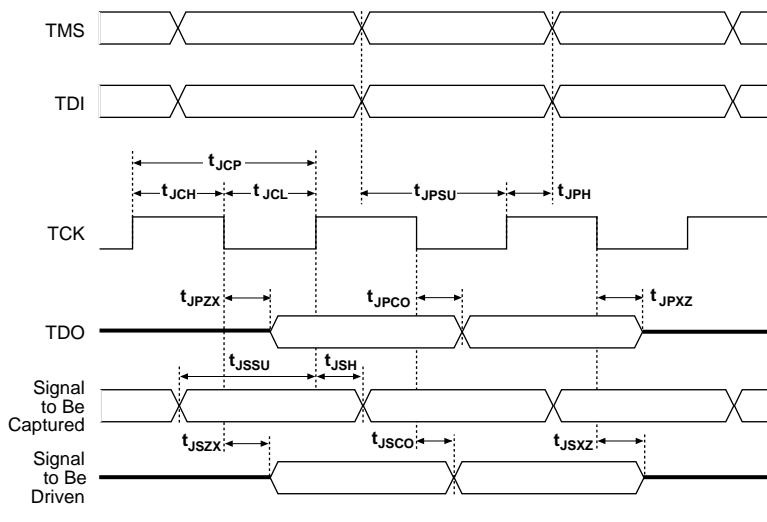
**Figure 8. MAX 7000B JTAG Waveforms**


Table 9 shows the JTAG timing parameters and values for MAX 7000B devices.

Symbol	Parameter	Min	Max	Unit
$t_{JCP}$	TCK clock period	100		ns
$t_{JCH}$	TCK clock high time	50		ns
$t_{JCL}$	TCK clock low time	50		ns
$t_{JPSU}$	JTAG port setup time	20		ns
$t_{JPH}$	JTAG port hold time	45		ns
$t_{JPCO}$	JTAG port clock to output		25	ns
$t_{JPZX}$	JTAG port high impedance to valid output		25	ns
$t_{JPXZ}$	JTAG port valid output to high impedance		25	ns
$t_{JSSU}$	Capture register setup time	20		ns
$t_{JSH}$	Capture register hold time	45		ns
$t_{JSCO}$	Update register clock to output		25	ns
$t_{JSZX}$	Update register high impedance to valid output		25	ns
$t_{JSXZ}$	Update register valid output to high impedance		25	ns

**Note:**

(1) Timing parameters in this table apply to all  $V_{CCIO}$  levels.

## Programmable Pull-Up Resistor

Each MAX 7000B device I/O pin provides an optional programmable pull-up resistor during user mode. When this feature is enabled for an I/O pin, the pull-up resistor (typically 50 k<sup>3/4</sup>) weakly holds the output to V<sub>CCIO</sub> level.

## Bus Hold

Each MAX 7000B device I/O pin provides an optional bus-hold feature. When this feature is enabled for an I/O pin, the bus-hold circuitry weakly holds the signal at its last driven state. By holding the last driven state of the pin until the next input signals is present, the bus-hold feature can eliminate the need to add external pull-up or pull-down resistors to hold a signal level when the bus is tri-stated. The bus-hold circuitry also pulls undriven pins away from the input threshold voltage where noise can cause unintended high-frequency switching. This feature can be selected individually for each I/O pin. The bus-hold output will drive no higher than V<sub>CCIO</sub> to prevent overdriving signals. The propagation delays through the input and output buffers in MAX 7000B devices are not affected by whether the bus-hold feature is enabled or disabled.

The bus-hold circuitry weakly pulls the signal level to the last driven state through a resistor with a nominal resistance (R<sub>BH</sub>) of approximately 8.5 k<sup>3/4</sup>. Table 12 gives specific sustaining current that will be driven through this resistor and overdrive current that will identify the next driven input level. This information is provided for each V<sub>CCIO</sub> voltage level.

**Table 12. Bus Hold Parameters**

Parameter	Conditions	VCCIO Level						Units
		1.8 V		2.5 V		3.3 V		
		Min	Max	Min	Max	Min	Max	
Low sustaining current	V <sub>IN</sub> > V <sub>IL</sub> (max)	30		50		70		μA
High sustaining current	V <sub>IN</sub> < V <sub>IH</sub> (min)	-30		-50		-70		μA
Low overdrive current	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>		200		300		500	μA
High overdrive current	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>		-295		-435		-680	μA

The bus-hold circuitry is active only during user operation. At power-up, the bus-hold circuit initializes its initial hold value as V<sub>CC</sub> approaches the recommended operation conditions. When transitioning from ISP to User Mode with bus hold enabled, the bus-hold circuit captures the value present on the pin at the end of programming.

**Table 15. MAX 7000B Device Recommended Operating Conditions**

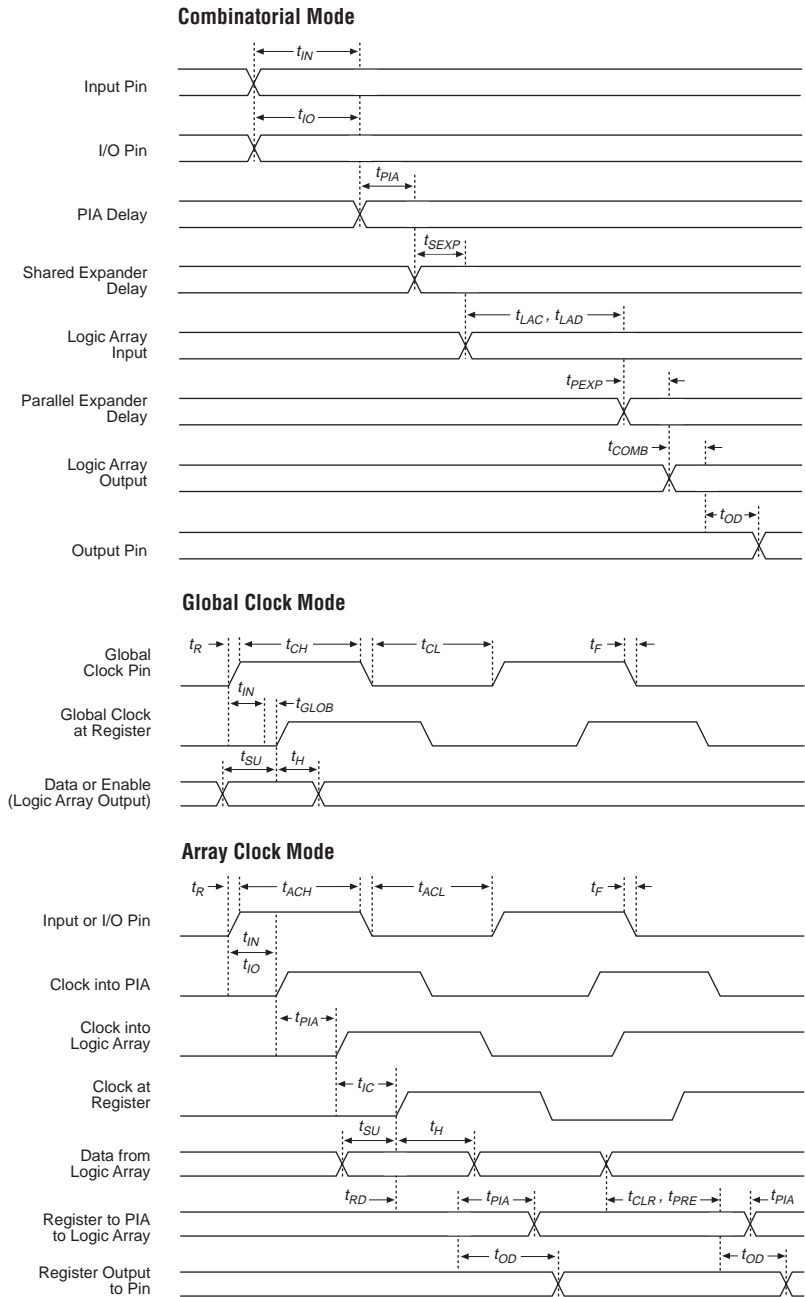
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CCINT</sub>	Supply voltage for internal logic and input buffers	(10)	2.375	2.625	V
V <sub>CCIO</sub>	Supply voltage for output drivers, 3.3-V operation		3.0	3.6	V
	Supply voltage for output drivers, 2.5-V operation		2.375	2.625	V
	Supply voltage for output drivers, 1.8-V operation		1.71	1.89	V
V <sub>CCISP</sub>	Supply voltage during in-system programming		2.375	2.625	V
V <sub>I</sub>	Input voltage	(3)	-0.5	3.9	V
V <sub>O</sub>	Output voltage		0	V <sub>CCIO</sub>	V
T <sub>A</sub>	Ambient temperature	For commercial use	0	70	°C
		For industrial use (11)	-40	85	°C
T <sub>J</sub>	Junction temperature	For commercial use	0	90	°C
		For industrial use (11)	-40	105	°C
t <sub>R</sub>	Input rise time			40	ns
t <sub>F</sub>	Input fall time			40	ns

Table 16. MAX 7000B Device DC Operating Conditions *Note (4)*

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>IH</sub>	High-level input voltage for 3.3-V TTL/CMOS		2.0	3.9	V
	High-level input voltage for 2.5-V TTL/CMOS		1.7	3.9	V
	High-level input voltage for 1.8-V TTL/CMOS		0.65 × V <sub>CCIO</sub>	3.9	V
V <sub>IL</sub>	Low-level input voltage for 3.3-V TTL/CMOS and PCI compliance		-0.5	0.8	V
	Low-level input voltage for 2.5-V TTL/CMOS		-0.5	0.7	V
	Low-level input voltage for 1.8-V TTL/CMOS		-0.5	0.35 × V <sub>CCIO</sub>	
V <sub>OH</sub>	3.3-V high-level TTL output voltage	I <sub>OH</sub> = -8 mA DC, V <sub>CCIO</sub> = 3.00 V (5)	2.4		V
	3.3-V high-level CMOS output voltage	I <sub>OH</sub> = -0.1 mA DC, V <sub>CCIO</sub> = 3.00 V (5)	V <sub>CCIO</sub> - 0.2		V
	2.5-V high-level output voltage	I <sub>OH</sub> = -100 μA DC, V <sub>CCIO</sub> = 2.30 V (5)	2.1		V
		I <sub>OH</sub> = -1 mA DC, V <sub>CCIO</sub> = 2.30 V (5)	2.0		V
		I <sub>OH</sub> = -2 mA DC, V <sub>CCIO</sub> = 2.30 V (5)	1.7		V
1.8-V high-level output voltage	I <sub>OH</sub> = -2 mA DC, V <sub>CCIO</sub> = 1.65 V (5)	1.2		V	
V <sub>OL</sub>	3.3-V low-level TTL output voltage	I <sub>OL</sub> = 8 mA DC, V <sub>CCIO</sub> = 3.00 V (6)		0.4	V
	3.3-V low-level CMOS output voltage	I <sub>OL</sub> = 0.1 mA DC, V <sub>CCIO</sub> = 3.00 V (6)		0.2	V
	2.5-V low-level output voltage	I <sub>OL</sub> = 100 μA DC, V <sub>CCIO</sub> = 2.30 V (6)		0.2	V
		I <sub>OL</sub> = 1 mA DC, V <sub>CCIO</sub> = 2.30 V (6)		0.4	V
		I <sub>OL</sub> = 2 mA DC, V <sub>CCIO</sub> = 2.30 V (6)		0.7	V
1.8-V low-level output voltage	I <sub>OL</sub> = 2 mA DC, V <sub>CCIO</sub> = 1.7 V (6)		0.4	V	
I <sub>I</sub>	Input leakage current	V <sub>I</sub> = -0.5 to 3.9 V (7)	-10	10	μA
I <sub>OZ</sub>	Tri-state output off-state current	V <sub>I</sub> = -0.5 to 3.9 V (7)	-10	10	μA
R <sub>ISP</sub>	Value of I/O pin pull-up resistor during in-system programming or during power up	V <sub>CCIO</sub> = 1.7 to 3.6 V (8)	20	74	k <sup>3</sup> / <sub>4</sub>

Figure 14. MAX 7000B Switching Waveforms

$t_R$  &  $t_F < 2$  ns. Inputs are driven at 3.0 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.





Tables 18 through 32 show MAX 7000B device timing parameters.

Symbol	Parameter	Conditions	Speed Grade						Unit
			-3.5		-5.0		-7.5		
			Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	$C1 = 35 \text{ pF}$ (2)		3.5		5.0		7.5	ns
$t_{PD2}$	I/O input to non-registered output	$C1 = 35 \text{ pF}$ (2)		3.5		5.0		7.5	ns
$t_{SU}$	Global clock setup time	(2)	2.1		3.0		4.5		ns
$t_H$	Global clock hold time	(2)	0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		1.0		1.0		1.5		ns
$t_{FH}$	Global clock hold time of fast input		1.0		1.0		1.0		ns
$t_{FZHSU}$	Global clock setup time of fast input with zero hold time		2.0		2.5		3.0		ns
$t_{FZH}$	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
$t_{CO1}$	Global clock to output delay	$C1 = 35 \text{ pF}$	1.0	2.4	1.0	3.4	1.0	5.0	ns
$t_{CH}$	Global clock high time		1.5		2.0		3.0		ns
$t_{CL}$	Global clock low time		1.5		2.0		3.0		ns
$t_{ASU}$	Array clock setup time	(2)	0.9		1.3		1.9		ns
$t_{AH}$	Array clock hold time	(2)	0.2		0.3		0.6		ns
$t_{ACO1}$	Array clock to output delay	$C1 = 35 \text{ pF}$ (2)	1.0	3.6	1.0	5.1	1.0	7.6	ns
$t_{ACH}$	Array clock high time		1.5		2.0		3.0		ns
$t_{ACL}$	Array clock low time		1.5		2.0		3.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset		1.5		2.0		3.0		ns
$t_{CNT}$	Minimum global clock period	(2)		3.3		4.7		7.0	ns
$f_{CNT}$	Maximum internal global clock frequency	(2), (3)	303.0		212.8		142.9		MHz
$t_{ACNT}$	Minimum array clock period	(2)		3.3		4.7		7.0	ns
$f_{ACNT}$	Maximum internal array clock frequency	(2), (3)	303.0		212.8		142.9		MHz

**Table 23. EPM7064B Selectable I/O Standard Timing Adder Delays (Part 1 of 2)** *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-3		-5		-7		
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.4		0.6	ns
	Input to global clock and clear		0.3		0.4		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.7		1.1	ns
	Input to global clock and clear		0.5		0.7		1.1	ns
	Input to fast input register		0.4		0.6		0.9	ns
	All outputs		1.2		1.7		2.6	ns
SSTL-2 Class I	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.7		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.7		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		-0.1		-0.1		-0.2	ns
SSTL-3 Class I	Input to PIA		1.2		1.7		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.2		1.7		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.6		2.3		3.4	ns
	Input to global clock and clear		1.6		2.3		3.4	ns
	Input to fast input register		1.5		2.1		3.2	ns
	All outputs		0.0		0.0		0.0	ns

I/O Standard	Parameter	Speed Grade						Unit
		-3		-5		-7		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

**Notes to tables:**

- (1) These values are specified under the Recommended Operating Conditions in [Table 15 on page 29](#). See [Figure 14](#) for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of all LABs.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

Table 28. EPM7256B Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.4		0.6		0.8	ns
$t_{IO}$	I/O input pad and buffer delay			0.4		0.6		0.8	ns
$t_{FIN}$	Fast input delay			1.5		2.5		3.1	ns
$t_{FIND}$	Programmable delay adder for fast input			1.5		1.5		1.5	ns
$t_{SEXP}$	Shared expander delay			1.5		2.3		3.0	ns
$t_{PEXP}$	Parallel expander delay			0.4		0.6		0.8	ns
$t_{LAD}$	Logic array delay			1.7		2.5		3.3	ns
$t_{LAC}$	Logic control array delay			1.5		2.2		2.9	ns
$t_{IOE}$	Internal output enable delay			0.1		0.2		0.3	ns
$t_{OD1}$	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.9		1.4		1.9	ns
$t_{OD3}$	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		5.9		6.4		6.9	ns
$t_{ZX1}$	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		2.2		3.3		4.5	ns
$t_{ZX3}$	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		7.2		8.3		9.5	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		2.2		3.3		4.5	ns
$t_{SU}$	Register setup time		1.2		1.8		2.5		ns
$t_H$	Register hold time		0.6		1.0		1.3		ns
$t_{FSU}$	Register setup time of fast input		0.8		1.1		1.1		ns
$t_{FH}$	Register hold time of fast input		1.2		1.4		1.4		ns
$t_{RD}$	Register delay			0.7		1.0		1.3	ns
$t_{COMB}$	Combinatorial delay			0.3		0.4		0.5	ns
$t_{IC}$	Array clock delay			1.5		2.3		3.0	ns
$t_{EN}$	Register enable time			1.5		2.2		2.9	ns
$t_{GLOB}$	Global control delay			1.3		2.1		2.7	ns
$t_{PRE}$	Register preset time			1.0		1.6		2.1	ns
$t_{CLR}$	Register clear time			1.0		1.6		2.1	ns
$t_{PIA}$	PIA delay	(2)		1.7		2.6		3.3	ns
$t_{LPA}$	Low-power adder	(4)		2.0		3.0		4.0	ns

<b>Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2)</b> <i>Note (1)</i>								
I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

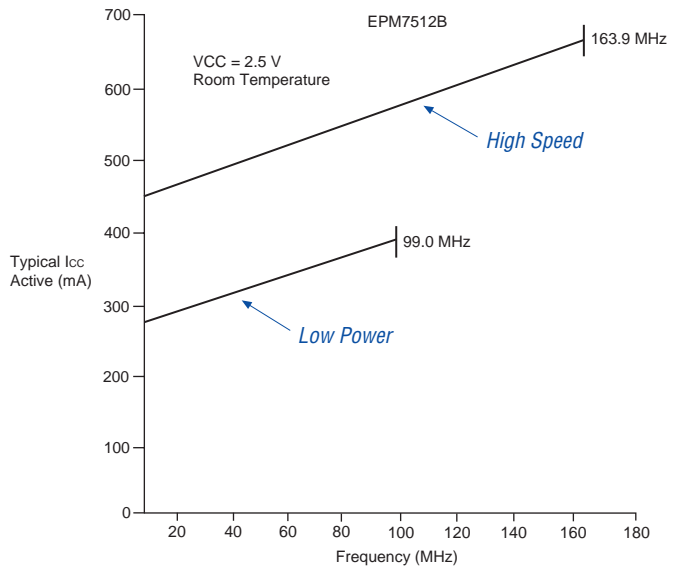
**Notes to tables:**

- (1) These values are specified under the Recommended Operating Conditions in [Table 15 on page 29](#). See [Figure 14](#) for more information on switching waveforms.
- (2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (4) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{CPPW}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

Table 31. EPM7512B Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.3		0.3		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.3		0.3		0.5	ns
$t_{FIN}$	Fast input delay			2.2		3.2		4.0	ns
$t_{FIND}$	Programmable delay adder for fast input			1.5		1.5		1.5	ns
$t_{SEXP}$	Shared expander delay			1.5		2.1		2.7	ns
$t_{PEXP}$	Parallel expander delay			0.4		0.5		0.7	ns
$t_{LAD}$	Logic array delay			1.7		2.3		3.0	ns
$t_{LAC}$	Logic control array delay			1.5		2.0		2.6	ns
$t_{IOE}$	Internal output enable delay			0.1		0.2		0.2	ns
$t_{OD1}$	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.9		1.2		1.6	ns
$t_{OD3}$	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		5.9		6.2		6.6	ns
$t_{ZX1}$	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		2.8		3.8		5.0	ns
$t_{ZX3}$	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		7.8		8.8		10.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		2.8		3.8		5.0	ns
$t_{SU}$	Register setup time		1.5		2.0		2.6		ns
$t_{H}$	Register hold time		0.4		0.5		0.7		ns
$t_{FSU}$	Register setup time of fast input		0.8		1.1		1.1		ns
$t_{FH}$	Register hold time of fast input		1.2		1.4		1.4		ns
$t_{RD}$	Register delay			0.5		0.7		1.0	ns
$t_{COMB}$	Combinatorial delay			0.2		0.3		0.4	ns
$t_{IC}$	Array clock delay			1.8		2.4		3.1	ns
$t_{EN}$	Register enable time			1.5		2.0		2.6	ns
$t_{GLOB}$	Global control delay			2.0		2.8		3.6	ns
$t_{PRE}$	Register preset time			1.0		1.4		1.9	ns
$t_{CLR}$	Register clear time			1.0		1.4		1.9	ns
$t_{PIA}$	PIA delay	(2)		2.4		3.4		4.5	ns
$t_{LPA}$	Low-power adder	(4)		2.0		2.7		3.6	ns

**Figure 19.  $I_{CC}$  vs. Frequency for EPM7512B Devices**



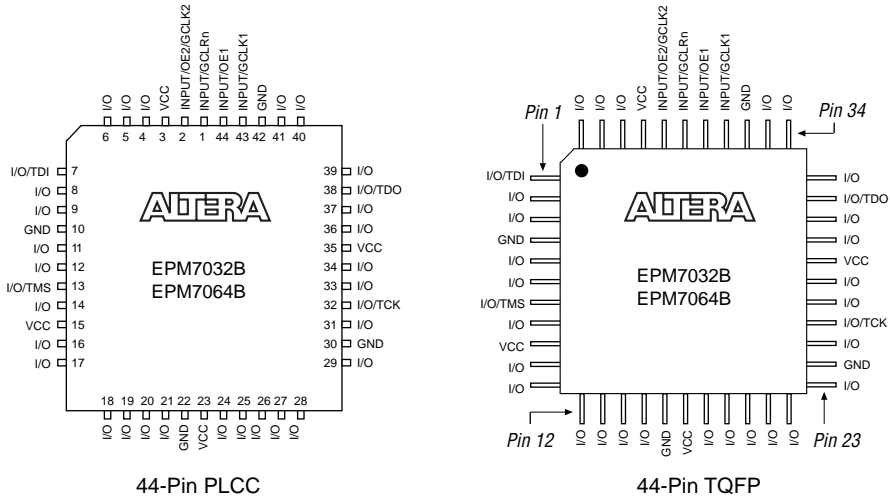
## Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information.

Figures 20 through 29 show the package pin-out diagrams for MAX 7000B devices.

**Figure 20. 44-Pin PLCC/TQFP Package Pin-Out Diagram**

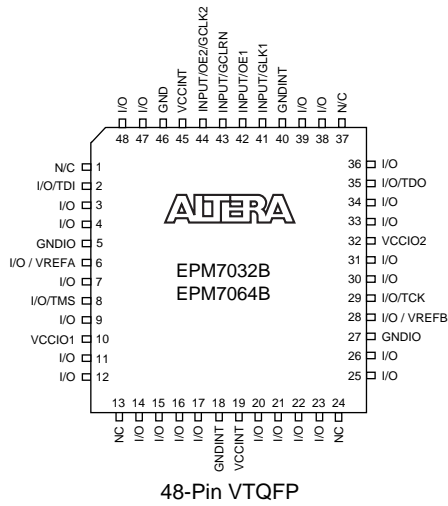
*Package outlines not drawn to scale.*





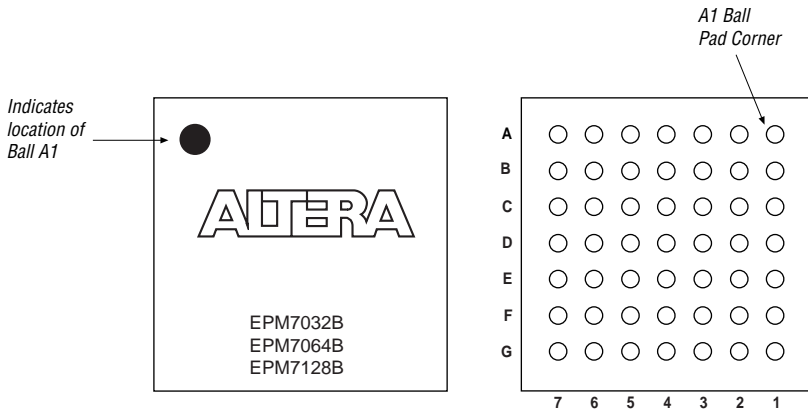
**Figure 21. 48-Pin VTQFP Package Pin-Out Diagram**

Package outlines not drawn to scale.



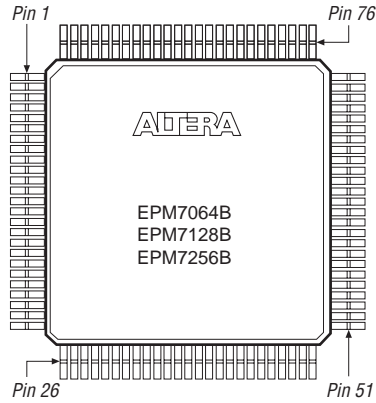
**Figure 22. 49-Pin Ultra FineLine BGA Package Pin-Out Diagram**

Package outline not drawn to scale.



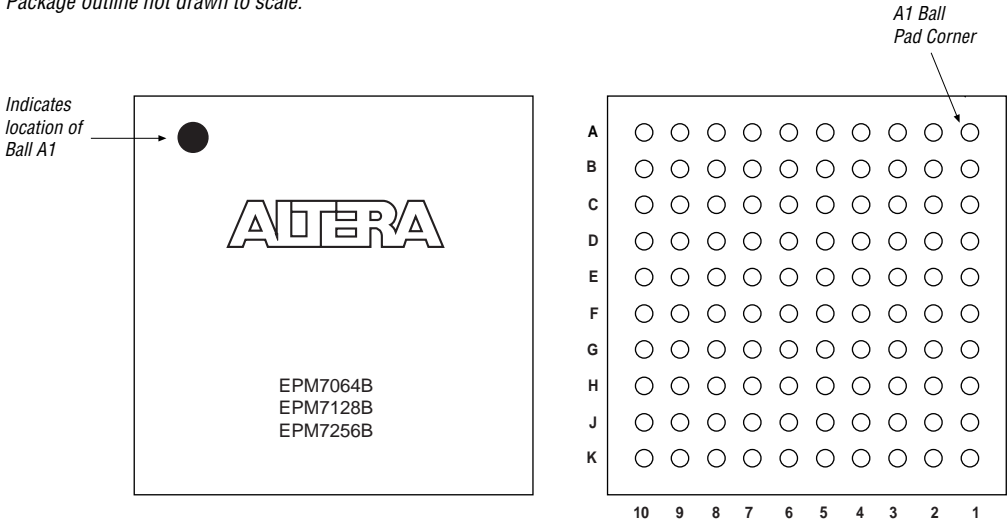
**Figure 23. 100-Pin TQFP Package Pin-Out Diagram**

Package outline not drawn to scale.



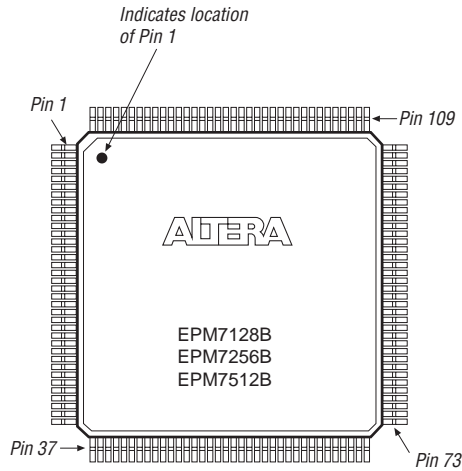
**Figure 24. 100-Pin FineLine BGA Package Pin-Out Diagram**

Package outline not drawn to scale.



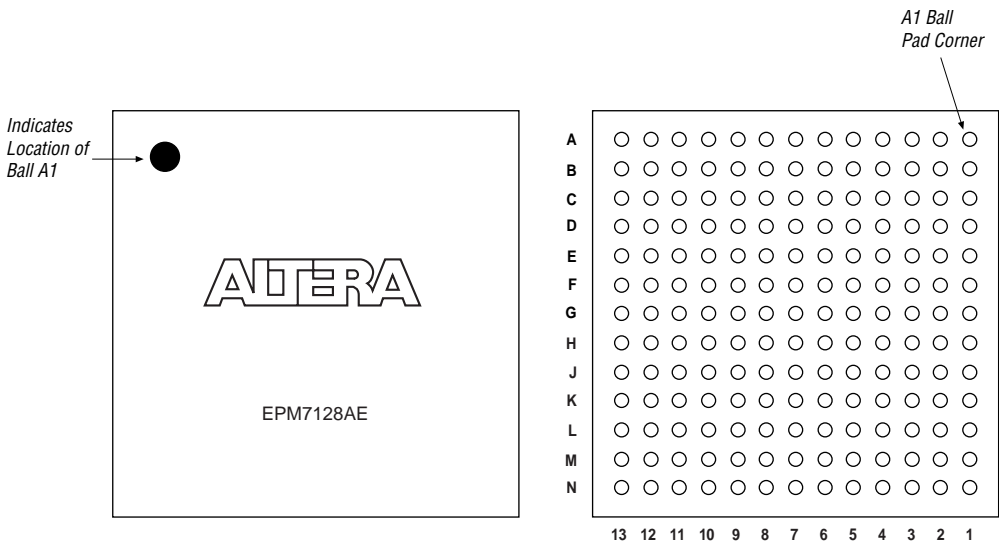
**Figure 25. 144-Pin TQFP Package Pin-Out Diagram**

*Package outline not drawn to scale.*



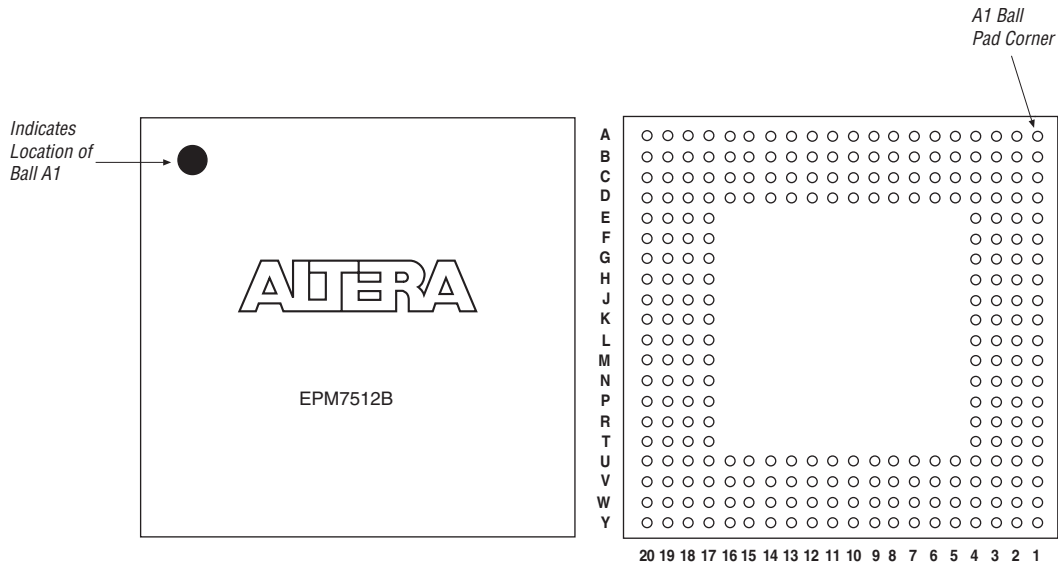
**Figure 26. 169-Pin Ultra FineLine BGA Pin-Out Diagram**

*Package outline not drawn to scale.*



**Figure 28. 256-Pin BGA Package Pin-Out Diagram**

Package outline not drawn to scale.



### Version 3.3

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.3:

- Updated [Table 3](#).
- Added [Tables 4](#) through [6](#).

### Version 3.2

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.2:

- Updated [Note \(10\)](#) and added ambient temperature ( $T_A$ ) information to [Table 15](#).

### Version 3.1

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.1:

- Updated  $V_{IH}$  and  $V_{IL}$  specifications in [Table 16](#).
- Updated leakage current conditions in [Table 16](#).

### Version 3.0

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.0:

- Updated timing numbers in [Table 1](#).
- Updated [Table 16](#).
- Updated timing in [Tables 18, 19, 21, 22, 24, 25, 27, 28, 30, and 31](#).



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